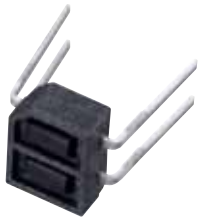
GP2S24J0000F Series

Detecting Distance : 0.7mm Phototransistor Output, Compact Reflective Photointerrupter



■ Description

GP2S24J0000F Series is a compact-package, phototransistor output, reflective photointerrupter, with emitter and detector facing the same direction in a molding that provides non-contact sensing. The compact package series is a result of unique technology, combing transfer and injection molding, that also blocks visible light to minimize false detection.

■ Features

1. Reflective with Phototransistor Output
2. Highlights :
   - Compact Size
3. Key Parameters :
   - Optimal Sensing Distance : 0.7mm
   - Package : 4×3×1.7mm
   - Visible light cut resin package
4. Lead free and RoHS directive compliant

■ Agency approvals/Compliance

1. Compliant with RoHS directive

■ Applications

1. Detection of object presence or motion.
2. Example : printer, optical storage

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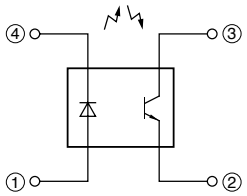
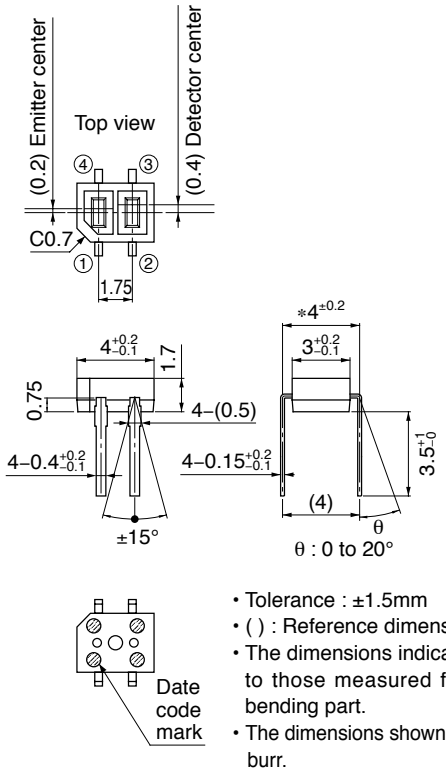
Date Oct. 3. 2005

■ Internal Connection Diagram



① Anode
② Emitter
③ Collector
④ Cathode

■ Outline Dimensions (Unit : mm)



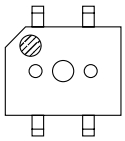
- Tolerance : ±1.5mm
- ( ) : Reference dimensions
- The dimensions indicated by ∗ refer to those measured from the lead bending part.
- The dimensions shown do not include burr.
  Burr's dimension : 0.15mm MAX.

Product mass : approx. 0.04g

Plating material : SnCu (Cu : TYP. 2%)

Date code (Symbol)

January



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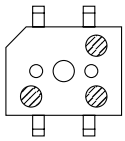
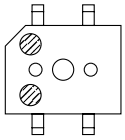


February



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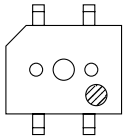
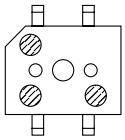


March



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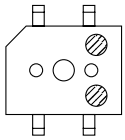

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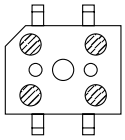
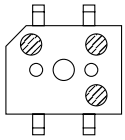


October



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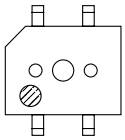

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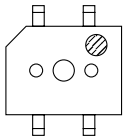

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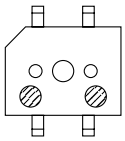

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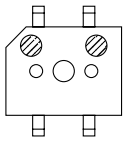


Rank mark

There is no rank indicator.

Country of origin

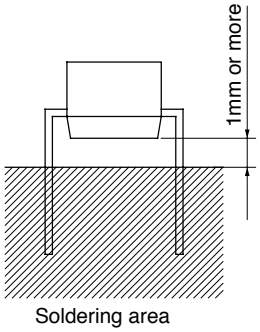
Japan

■ Absolute Maximum Ratings

(T_a=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	20	mA
	Collector power dissipation	P_C	75	mW
Total power dissipation		P_{tot}	100	mW
Operating temperature		T_{opr}	–25 to +85	°C
Storage temperature		T_{stg}	–40 to +100	°C
*1Soldering temperature		T_{sol}	260	°C

*1 For 5s or less



■ Electro-optical Characteristics

(T_a=25°C)

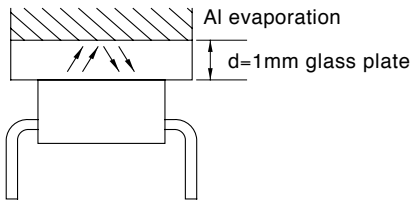
Parameter			Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V_F	I_F=20mA	–	1.2	1.4	V
	Reverse current		I_R	V_R=6V	–	–	10	μA
Output	Collector dark current		I_{CEO}	V_{CE}=20V	–	1	100	nA
Transfer characteristics	*2 Collector Current		I_C	I_F=4mA, V_{CE}=2V	20	45	120	μA
	Response time	Rise time	t_r	V_{CE}=2V, I_C=100μA,	–	20	100	μs
		Fall time	t_f	R_L=1kΩ, d=1mm	–	20	100	
	*3 Leak current		I_{LEAK}	I_F=4mA, V_{CE}=2V	–	–	100	nA

*2 The condition and arrangement of the reflective object are shown below.
The rank splitting of collector current (I_C) shall be executed according to the table below.

Rank	Collector current, I_C [μA] (I_F=4mA, V_{CE}=2V)	Package sleeve color
A	20 to 42	Yellow
B	34 to 71	Transparent
C	58 to 120	Green

*3 Without reflective object.

● Test Conditon and Arrangement for Collector Current



■ Model Line-up

Model No.	Rank	Collector current I_C[μA] (I_F=4mA, V_{CE}=2V, T_a=25°C)
GP2S24J0000F	A, B or C	20 to 120
GP2S24BJ000F	B	34 to 71
GP2S24CJ000F	C	58 to 120
GP2S24ABJ00F	A or B	20 to 71
GP2S24BCJ00F	B or C	34 to 120

* The ratio of each rank can not be guaranteed.

Please contact a local SHARP sales representative to inquire about production status.

Fig.1 Forward Current vs. Ambient Temperature

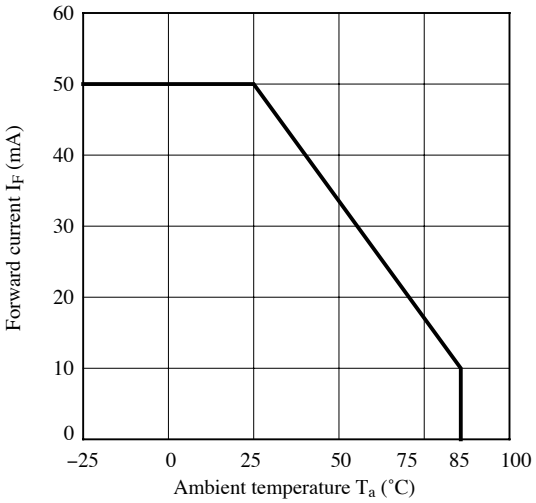


Fig.2 Power Dissipation vs. Ambient Temperature

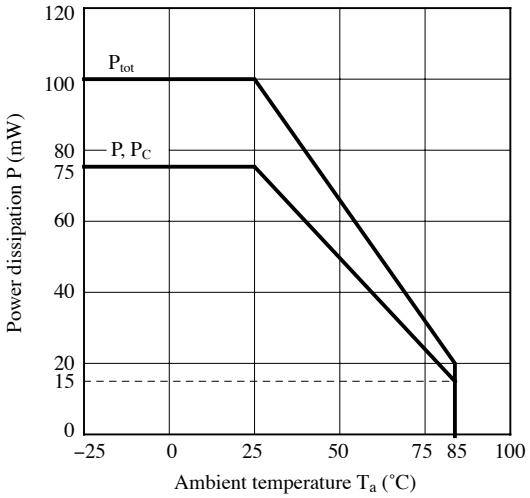


Fig.3 Forward Current vs. Forward Voltage

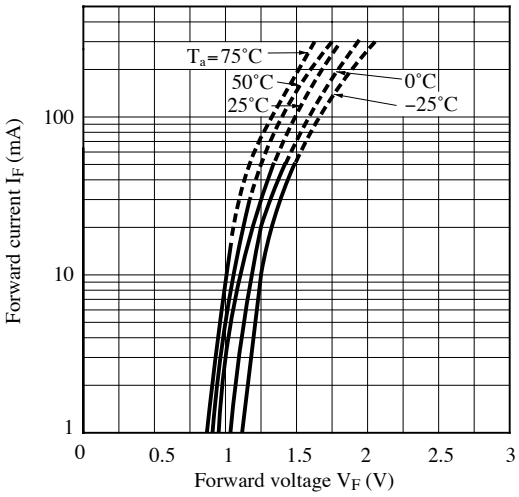


Fig.4 Collector Current vs. Forward Current

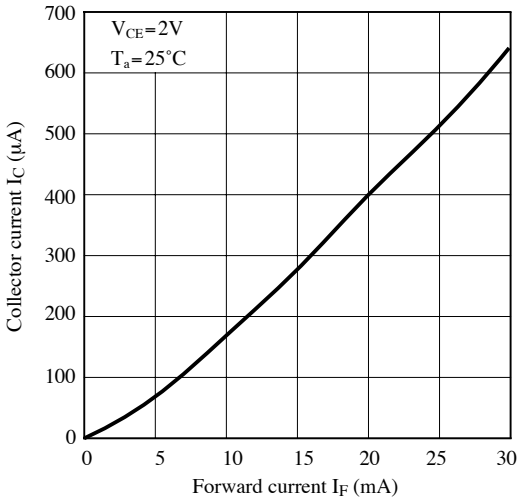


Fig.5 Collector Current vs. Collector-Emitter Voltage

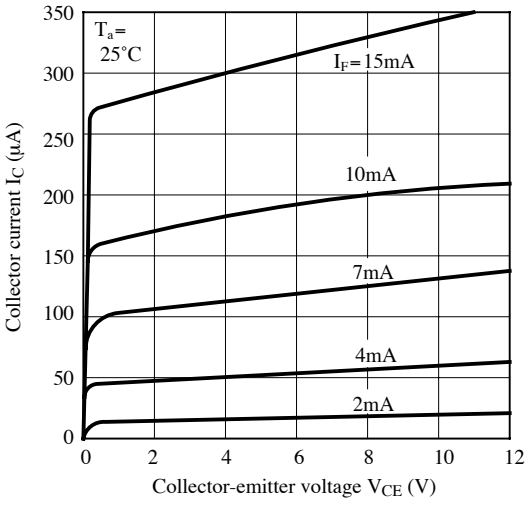


Fig.6 Relative Collector Current vs. Ambient Temperature

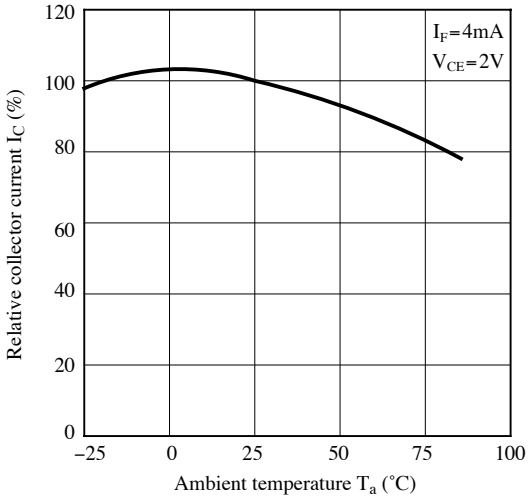


Fig.7 Collector Dark Current vs. Ambient Temperature

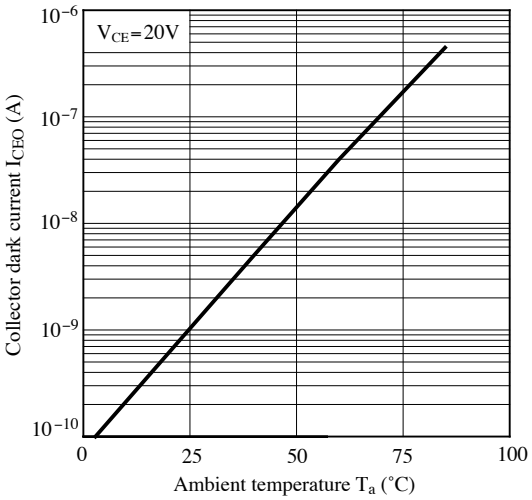


Fig.8 Response Time vs. Load Resistance

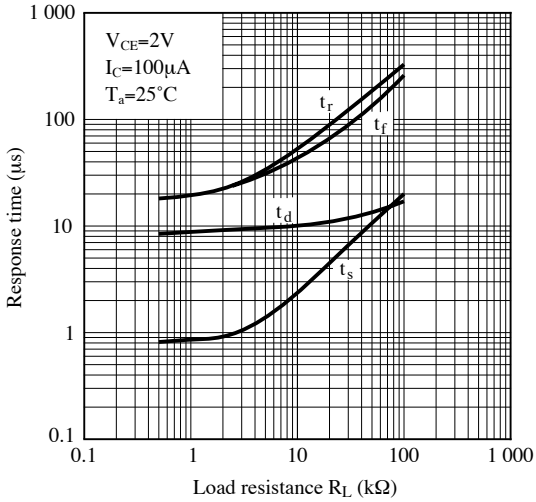


Fig.9 Test Circuit for Response Time

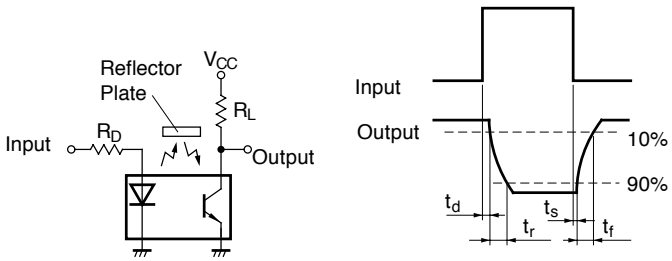


Fig.10 Relative Collector Current vs. Distance (Reference value)

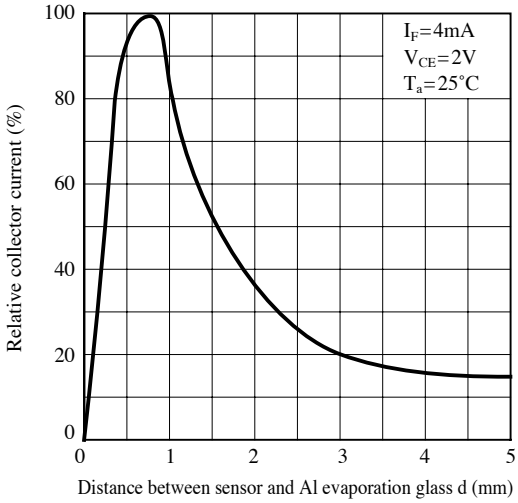


Fig.11 Detecting Position Characteristics (1)

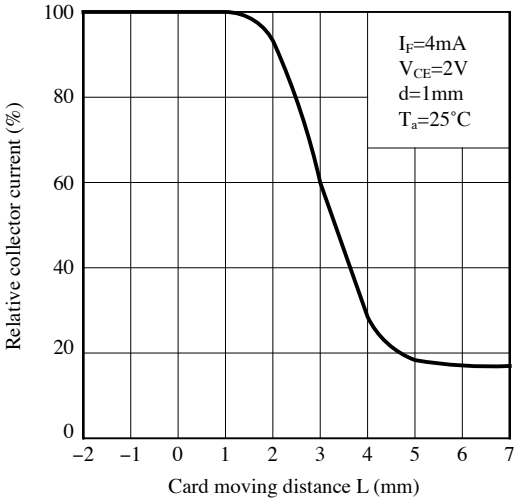


Fig.12 Detecting Position Characteristics (2)

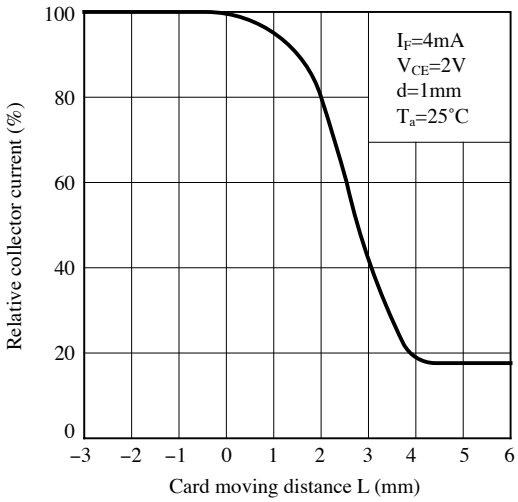


Fig.13 Test Condition for Distance & Detecting Position Characteristics

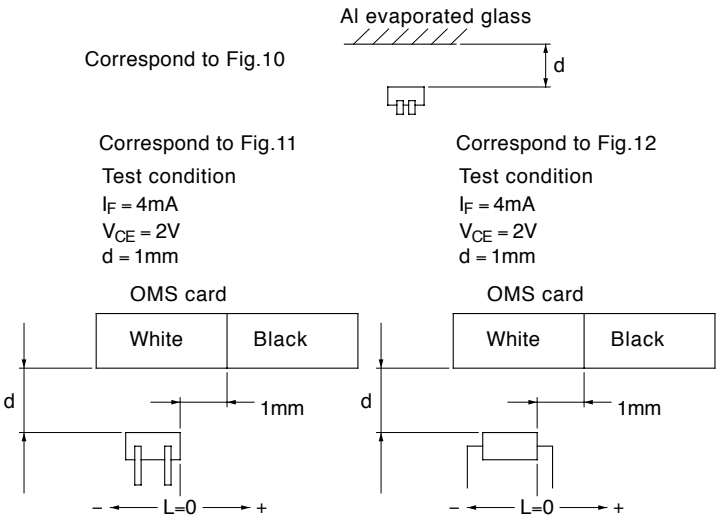


Fig.14 Freauency Response

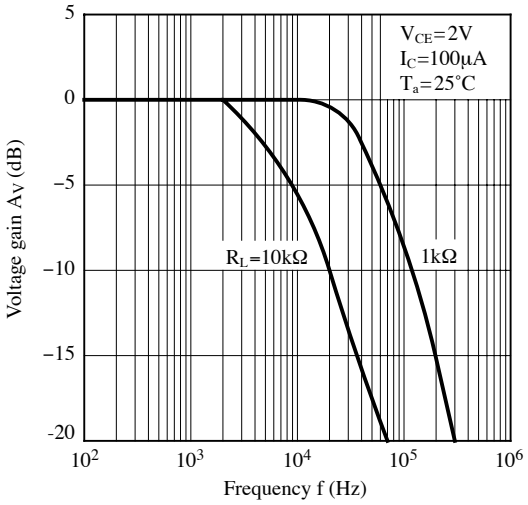
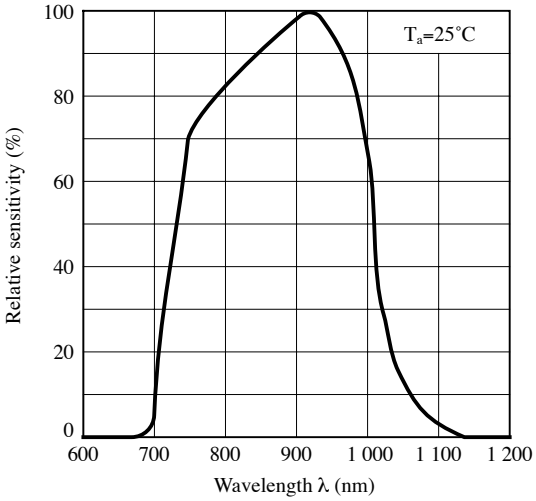


Fig.15 Spectral Sensitivity (Detecting Side)



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ Design Considerations

● Design guide

1) Prevention of detection error
To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

2) Distance characteristic
Please refer to Fig.10 (Relative collector current vs. Distance) to set the distance of the photointerrupter and the object.

This product is not designed against irradiation and incorporates non-coherent IRED.

● Degradation

In general, the emission of the IRED used in photointerrupter will degrade over time.
In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

● Parts

This product is assembled using the below parts.

• Photodetector (qty. : 1)

Category	Material	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (μs)
Phototransister	Silicon (Si)	930	700 to 1 200	20

• Photo emitter (qty. : 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3

• Material

Case	Lead frame	Lead frame plating
Black polyphernylene	42Alloy	SnCu plating

■ Manufacturing Guidelines

● Soldering Method

Flow Soldering:

Soldering should be completed below 260˚C and within 5 s.
Soldering area is 1mm or more away from the bottom of housing.
Please take care not to let any external force exert on lead pins.
Please don't do soldering with preheating, and please don't do soldering by reflow.

Other notice

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the cooling and soldering conditions.

● Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45˚C or below. Immersion time should be 3 minutes or less.

Ultrasonic cleaning :

Do not execute ultrasonic cleaning.

Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

● Presence of ODC

This product shall not contain the following materials.
And they are not used in the production process for this product.
Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

■ Package specification

● Sleeve package

Package materials

Sleeve : Polystyrene
Stopper : Styrene-Butadiene

Package method

MAX. 50 pcs. of products shall be packaged in a sleeve. Both ends shall be closed by tabbed and tabless stoppers.
MAX. 40 sleeves in one case.

Color of sleeve

Rank classification is distinguished by the color of the sleeve as shown in the table below.
But the ratio of each rank can not be guaranteed.

Rank	Color of sleeve
A	Yellow
B	Transparent
C	Green

■ Important Notices

· The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

--- Personal computers
--- Office automation equipment
--- Telecommunication equipment [terminal]
--- Test and measurement equipment
--- Industrial control
--- Audio visual equipment
--- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

--- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
--- Traffic signals
--- Gas leakage sensor breakers
--- Alarm equipment
--- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

--- Space applications
--- Telecommunication equipment [trunk lines]
--- Nuclear power control equipment
--- Medical and other life support equipment (e.g., scuba).

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